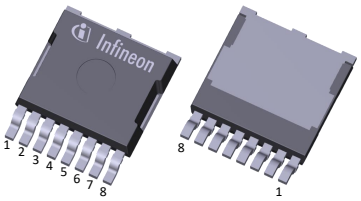
MOSFET

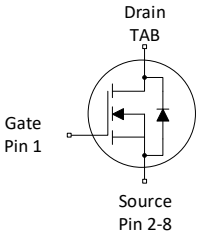
OptiMOS™ 5 Power-Transistor, 150 V

PG-HSOG-8



Features

- N-channel, normal level
- Very low on-resistance $R_{DS(on)}$
- Superior thermal resistance
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	150	V
$R_{DS(on),max}$	3.9	mΩ
I_D	190	A
Q_{oss}	207	nC
Q_G	74	nC

Hal Pb RoHS

Type/Ordering Code	Package	Marking	Related Links
IPTG039N15NM5	PG-HSOG-8	039N15N5	-

Table of Contents

1 Maximum ratings

unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Continuous drain current [1]	I_D	-	-	190 134 128 21	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=8 V, T_C=100 °C V_{GS}=10V, T_A=25°C, R_{thJA}=40°C/W [2]
Pulsed drain current [3]	$I_{D,pulse}$	-	-	760	A	T_A=25 °C
Avalanche energy, single pulse [4]	E_{AS}	-	-	344	mJ	I_D=100 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	319 3.8	W	T_C=25 °C T_A=25 °C, R_{thJA}=40 °C/W [2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

[3] See Diagram 3 for more detailed information

[4] See Diagram 13 for more detailed information

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.47	°C/W	-
Thermal resistance, junction - ambient, 6 cm² cooling area [5]	R_{thJA}	-	-	40	°C/W	-
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}	-	-	62	°C/W	-

[5] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	150	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	3.0	3.8	4.6	V	V_{DS}=V_{GS}, I_D=243 µA
Zero gate voltage drain current	I_{DSS}	-	0.1 10	1.0 100	µA	V_{DS}=120 V, V_{GS}=0 V, T_j=25 °C V_{DS}=120 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	3.5 3.8	3.9 4.3	mΩ	V_{GS}=10 V, I_D=50 A V_{GS}=8 V, I_D=25 A
Gate resistance [6]	R_G	-	1.1	1.6	Ω	-
Transconductance	g_{fs}	-	110	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=50 A

[6] Defined by design. Not subject to production test.

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Input capacitance [7]	C_{iss}	-	5600	7300	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Output capacitance [7]	C_{oss}	-	1400	1930	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Reverse transfer capacitance [7]	C_{rss}	-	31	55	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	19	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	4.5	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	23.5	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	5.5	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=50 A, $R_{G,ext}$=1.6 Ω

[7] Defined by design. Not subject to production test.

Table 6 Gate charge characteristics [8)]

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	30	-	nC	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	21	-	nC	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Gate to drain charge [9)]	Q_{gd}	-	15	22	nC	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	23	-	nC	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Gate charge total [9)]	Q_g	-	74	93	nC	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	5.4	-	V	V_{DD}=75 V, I_D=50 A, V_{GS}=0 to 10 V
Output charge [9)]	Q_{oss}	-	207	275	nC	V_{DS}=75 V, V_{GS}=0 V

[8)] See "Gate charge waveforms" for parameter definition

[9)] Defined by design. Not subject to production test.

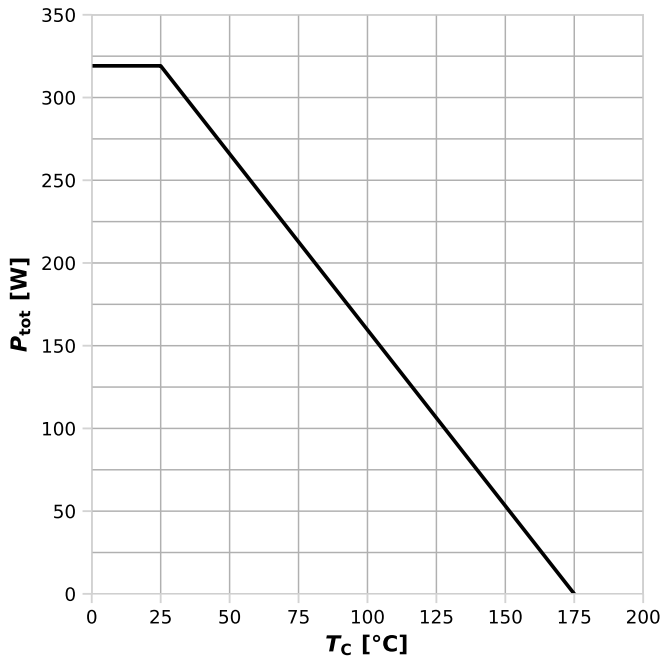
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note/ Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	190	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	760	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.81	1.0	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time [10)]	t_{rr}	-	53.5	107	ns	V_R=75 V, I_F=50 A, di_F/dt=100 A/µs
Reverse recovery charge [10)]	Q_{rr}	-	77	155	nC	V_R=75 V, I_F=50 A, di_F/dt=100 A/µs

[10)] Defined by design. Not subject to production test.

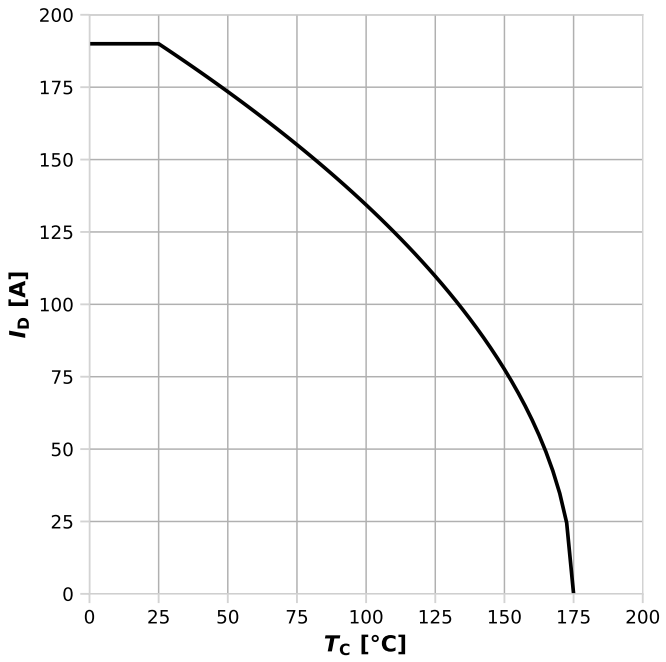
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



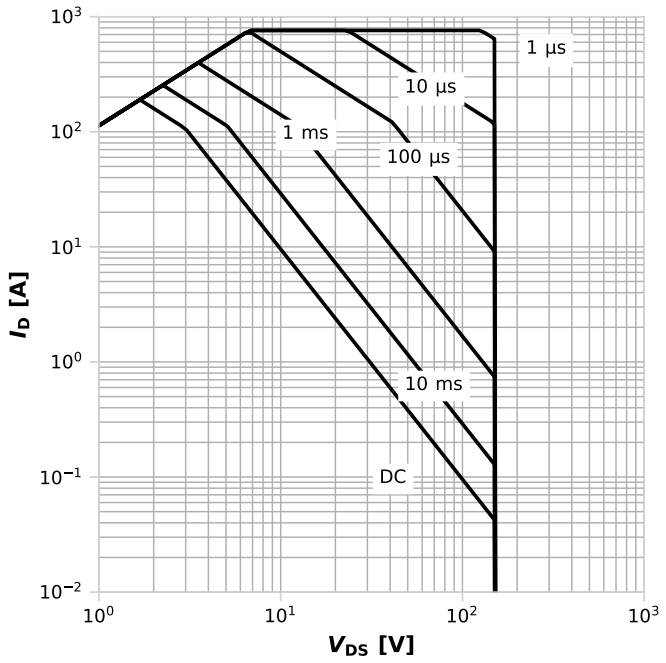
P_{tot}=f(T_C)

Diagram 2: Drain current



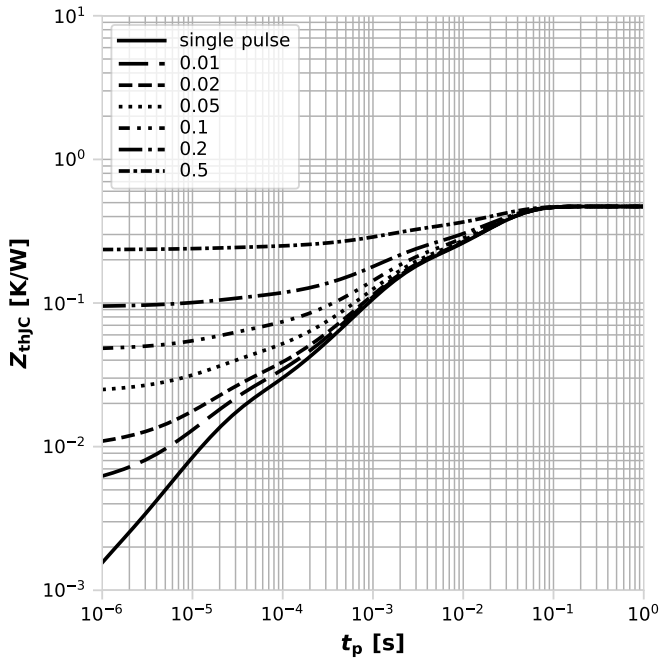
I_D=f(T_C); V_{GS}≥10 V

Diagram 3: Safe operating area



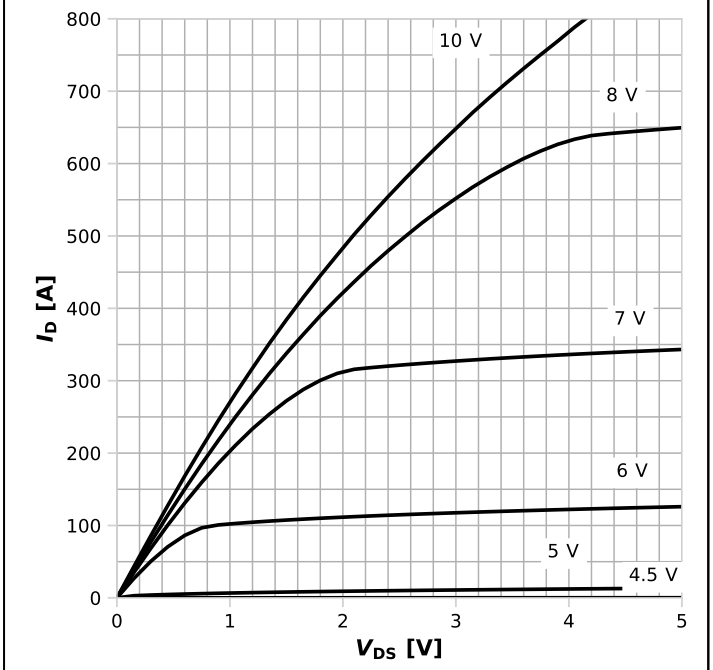
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 4: Max. transient thermal impedance



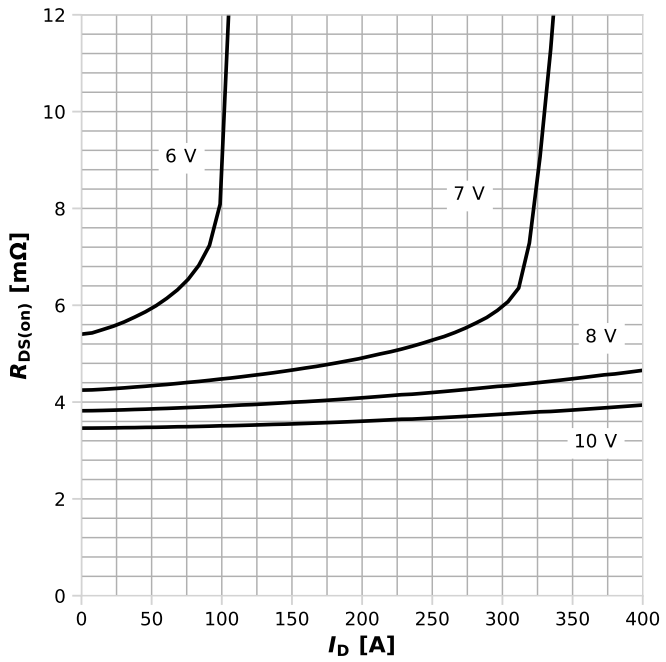
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 5: Typ. output characteristics



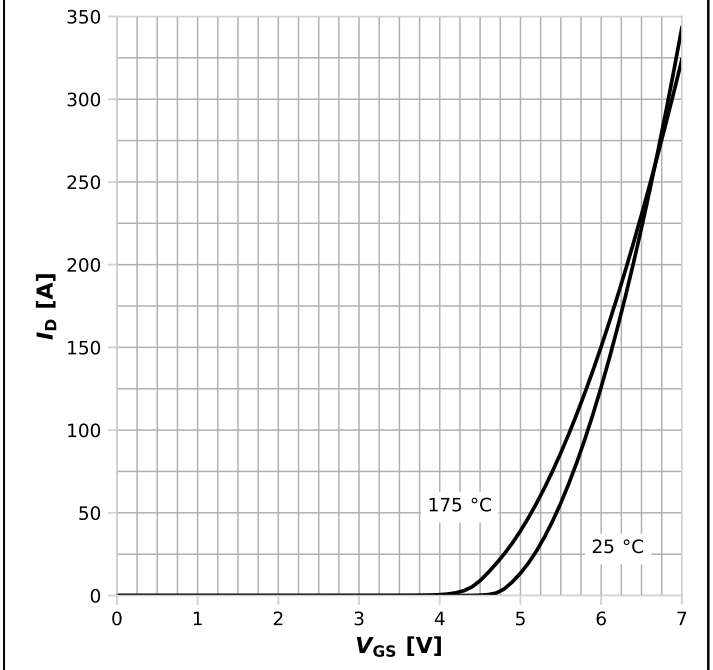
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



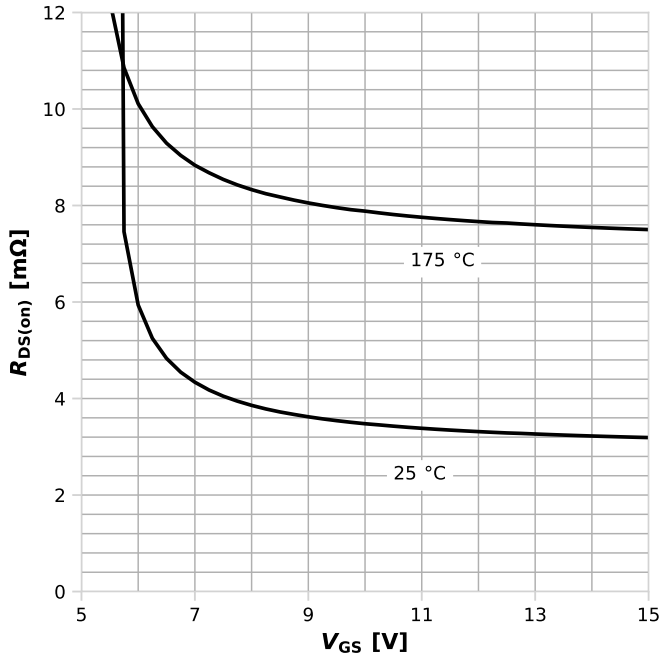
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



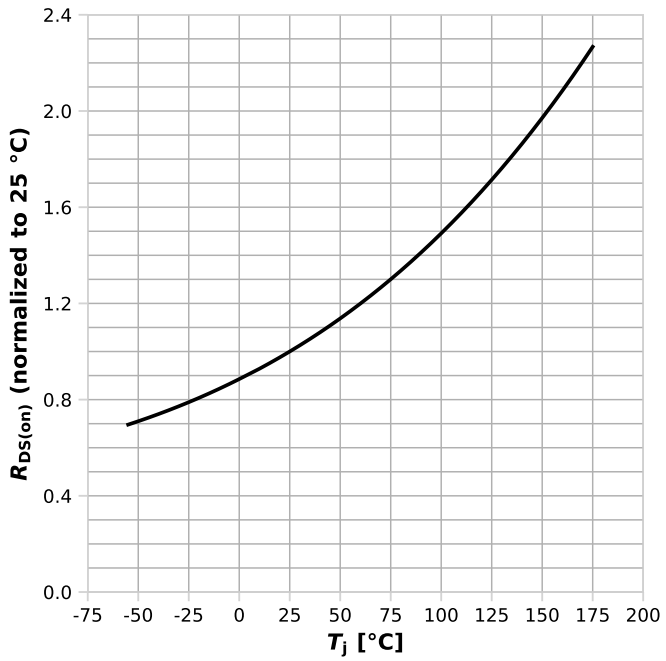
I_D=f(V_{GS}), |V_{DS}|>2|I_D|$R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



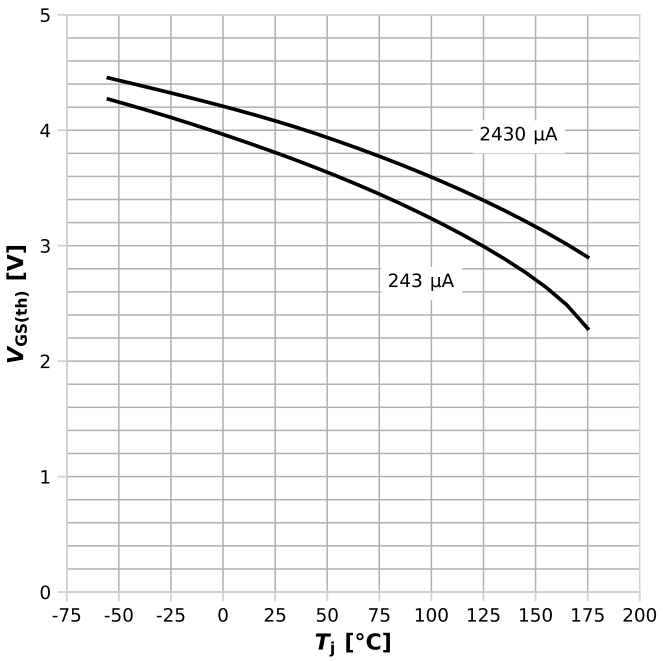
$R_{DS(on)}$=f(V_{GS}), I_D=50 A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



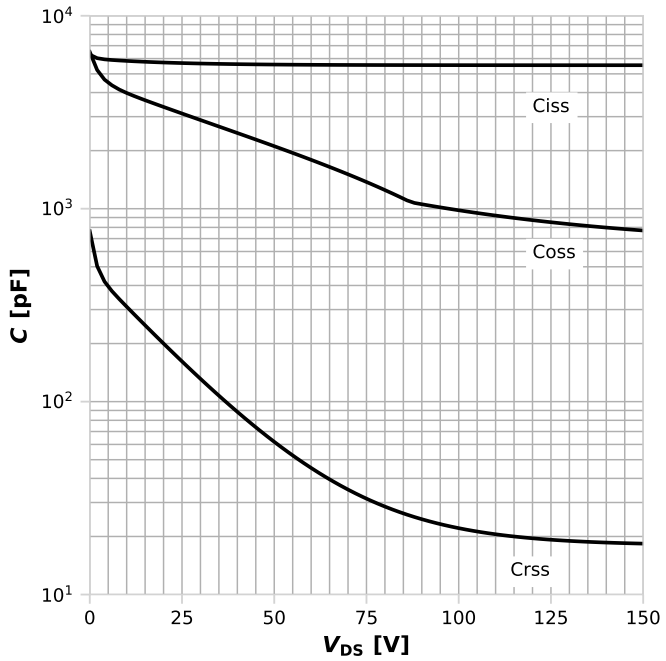
$R_{DS(on)}$=f(T_j), I_D=50 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



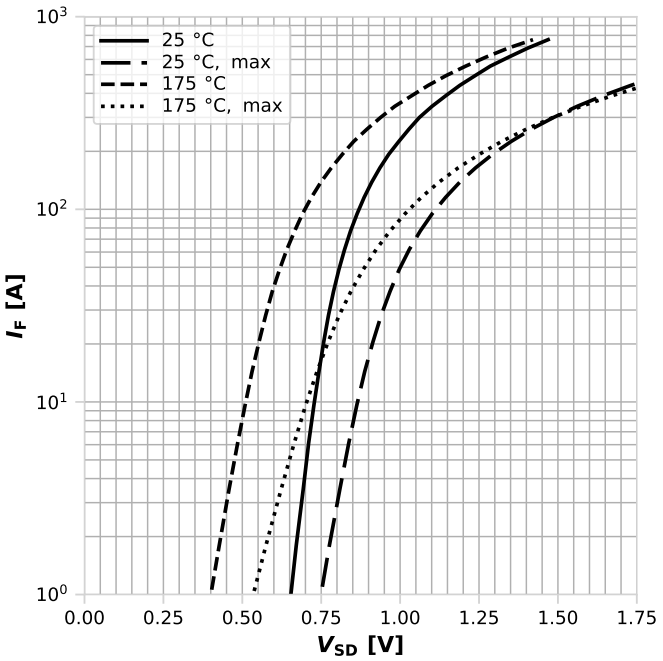
$V_{GS(th)}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

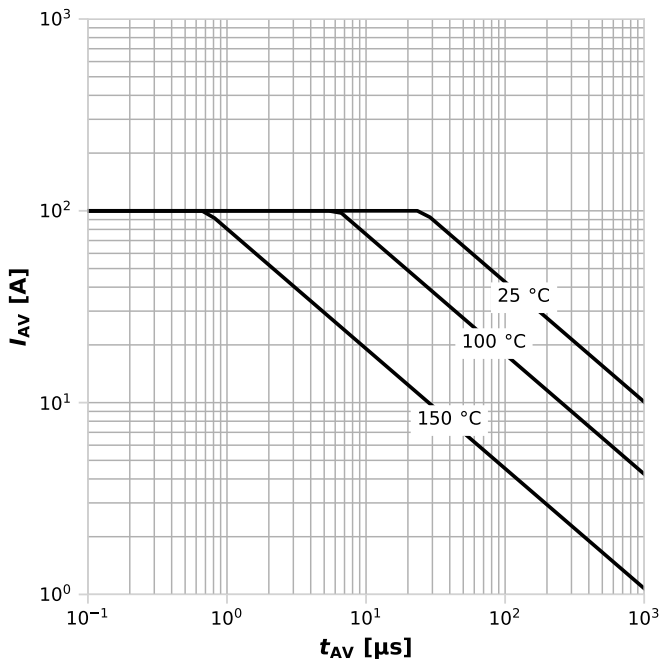
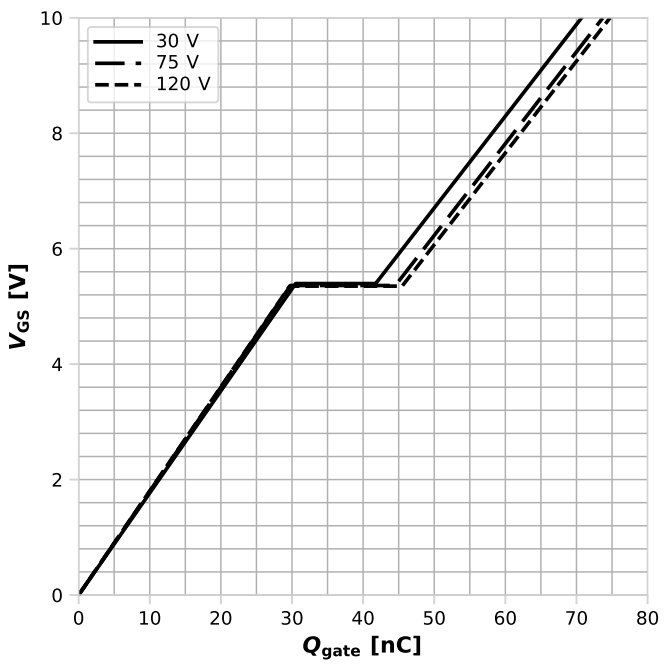
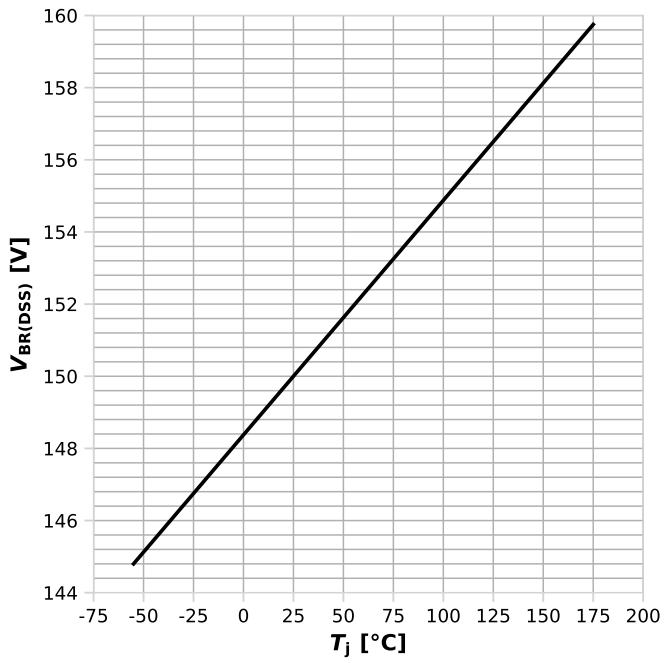
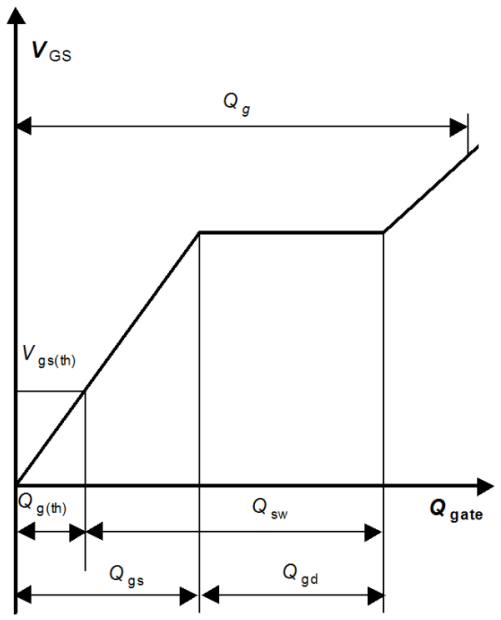
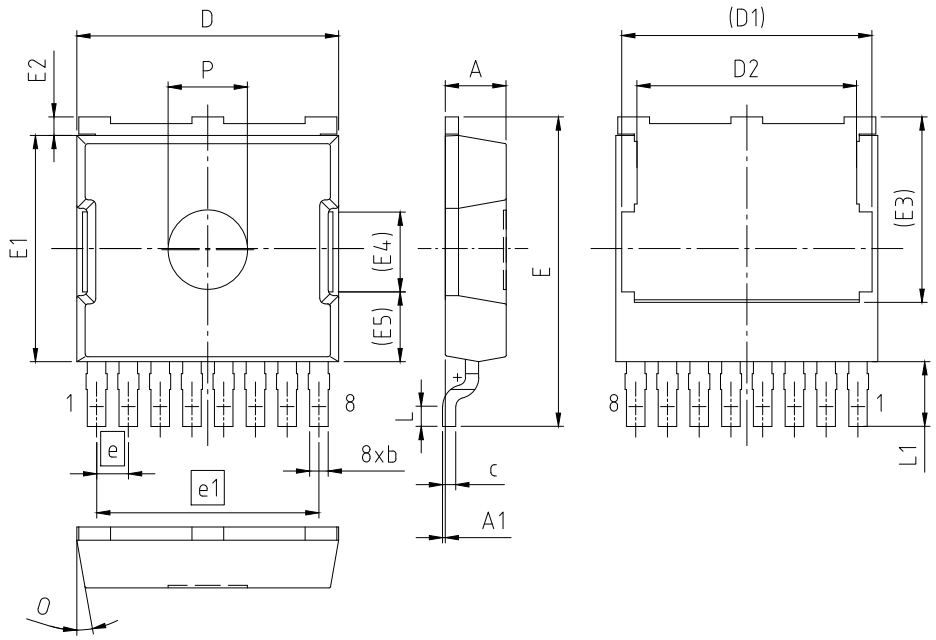
Diagram 13: Avalanche characteristics	Diagram 14: Typ. gate charge
	
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$	V_{GS}=f(Q_{gate}), I_D=50 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage	Gate charge waveforms
	
$V_{BR(DSS)}$=f(T_j); I_D=1 mA	-

5 Package Outlines



PACKAGE - GROUP NUMBER:	PG-HSOG-8-U01				
DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	2.20	2.40	e	1.20	
A1	0.00	0.10	e1	8.40	
b	0.60	0.80	L	0.66	0.86
c	0.40	0.60	L1	2.44	2.74
D	9.70	10.10	O	8°	12°
D1	9.46		P	2.90	3.10
D2	8.20	8.40			
E	11.50	11.90			
E1	8.45	8.75			
E2	0.50	0.90			
E3	7.01				
E4	3.02				
E5	2.64				

NOTE: DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS

Figure 1 Outline PG-HSOG-8, dimensions in mm

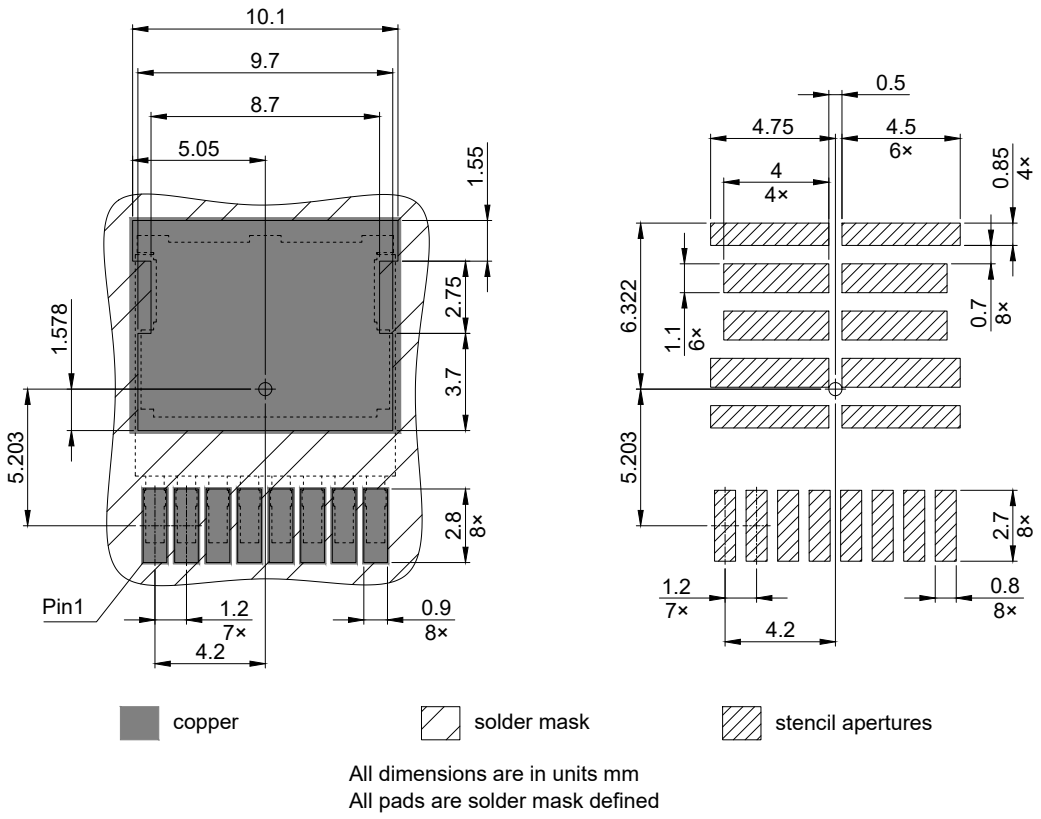


Figure 2 Outline PG-HSOG-8, dimensions in mm

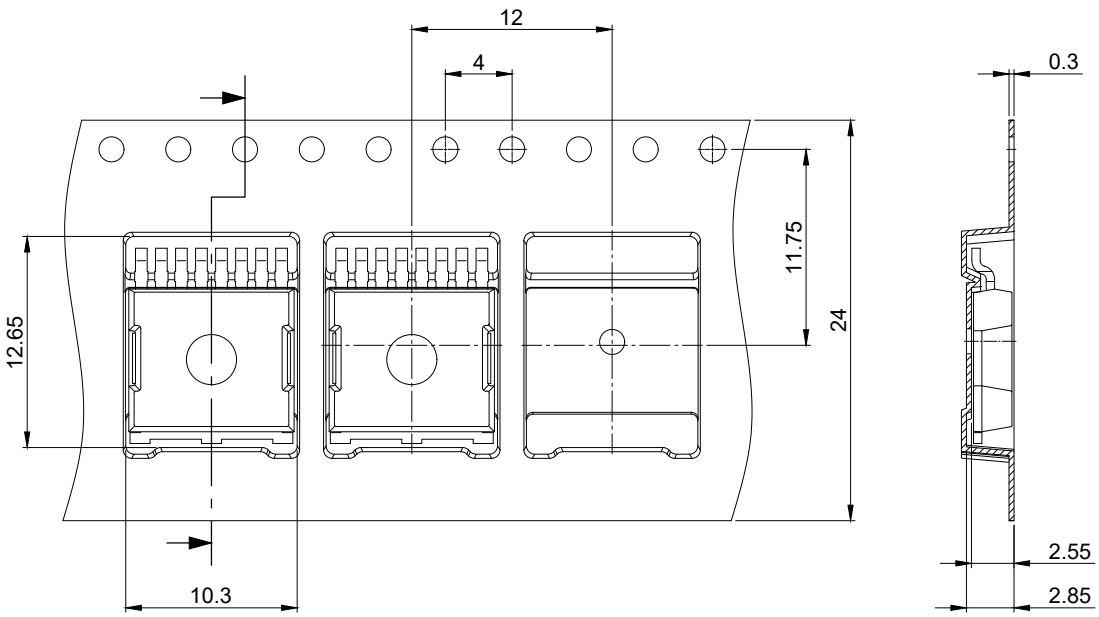


Figure 3 Outline PG-HSOG-8, dimensions in mm

Revision History

IPTG039N15NM5

Revision 2024-06-11, Rev. 2.2

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2022-05-05	Release of final version
2.1	2023-03-13	Update Coss max
2.2	2024-06-11	Update Rg

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